注塑机连动型高速溅射・聚合系统

Metal films and protective films on resin substrates

Injection molding machine linked high speed sputtering / polymerization system

SPP-202-H

can be formed fully automatically!

点】

1. 全自动: 可在注模成型的基板上全自动地进行真空成膜(溅射和聚合)。

2. 循环时间: 100秒 (AI: 100nm+SiOx: 20nm)

3. 高度粘合: 即使无底涂层亦可获得高粘合性。

[Features]

1. full automatic: Injection molded substrates can be vacuum-deposited (sputtering and polymerization) fully automatically.

2. Cycle time: 100seconds (Al: 100 nm + SiOx: 20 nm)

3. High degree of adhesion: High adhesion can be obtained even without an undercoat.

【目标产品】

汽车前照灯反射器/镜子/金属装饰膜

[Applications]

Car headlamp reflector / Mirror / Metal decorative film



有的机型可连接到成型机

There is also a type that connects to a molding machine

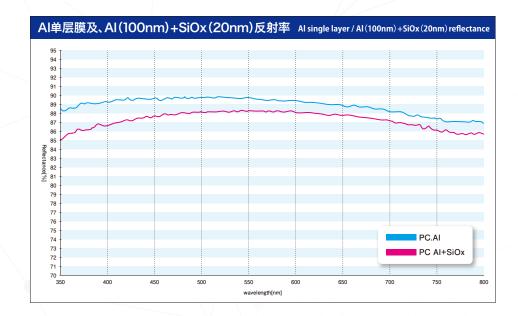
SPP-SERIES

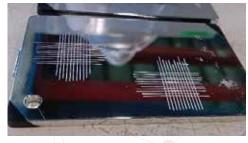
金属膜 + 保护膜沉积系统

Metal and protective film coating system

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PC基板 无打底膜层 AI镀膜后划成十字格状态, 没有发现薄膜脱落。

PC substrate, under coating film less. After coating Al and cutting it to across, a film don't peel off.

设备结构 Device configuration

最大装载尺寸 W250×L500×D150mm Maximum substrate size W250×L500×D150mm

Maximum substrate size W250×L500×D150mm

适用基片材质 PC, PET, PP, PE等 Substrate material PC.PFT.PP.PE etc.

溅射数率 10nm/sec以上 (AI) Sputter rate 10nm or more / sec (AI)

聚合数率 lnm/sec Polymerized rate lnm/sec

抽气速度 40sec可达0.1Pa (溅射室), 40sec可达10Pa (聚合室)
Pumping speed 40sec to 0.1Pa (sputtering chamber), 40sec to 10Pa (polymerization chamber)

外理周期 自基片投放、溅镀、聚合至取出约在100sec以内完成。

处理周期 自基片投放、溅镀、聚合至取出约在100sec以内完成。

Cycle time of production from inputting substrate, through coating and polymerized, to output. Approx. 100sec or less

膜性能 反射率85%以上,KOH 1%10min Reflectance 85% or High, KOH 1% 10min

泵配置 溅射室: RP + MBP + TMP, 聚合室: RP + MBP (TMP选件)
Vacuum system Sputtering chamber: RP + MBP + TMP, polymerization chamber: RP + MBP (TMP option)

SP室+聚合室 2室配置

Chamber system 2 chambers system(sputter chamber and polymerized chamber)

溅镀室 高速率溅射阴极 (靶材尺寸540×240mm)、40KW DC电源 Sputter chamber High rate cathode (target size540×240mm), 40KW DC power supply

聚合室 辉光放电聚合电极×1个 lkW 射频电源

Polymerized chamber Polymerized electrode using glow discharge ×1 1kW RF power supply

溅射材料 AI等 Sputter Materials AI etc.

聚合气体 HMDSO (SiOx用) 等 Polymerized HMDSO (for SiOx) etc.

◇可选项 基板旋转机构 ◇ Option Board rotation mechanism

如您正在考虑新的镀膜方案的话, 务必和弊社进行商谈!

※本规格及设备外观,在设备改良有时会发生临时变更,恕不另行通知,恳请理解。

If you are looking for new film coating technology, Please ask our company!

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* For the improvement of the product, please understand in advance that the specifications and external views are subject to change without prior notice.



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This product may be applicable to export control products such as strategic raw materials which are regulated by the Foreign Exchange and Foreign Trade Control Law. Accordingly when you bring out the applicable products outside Japan, you should take a necessary action such as application of an export permit to the Government of Japan.

Web site 产品信息 Product Information

我们生产销售真空技术应用设备(真空设备),例如真空蒸镀设备和溅射设备等,主要是在真空中在特定基板上形成薄膜的设备。



SHOWA SHINKU manufactures and sells vacuum equipment such as Vacuum evaporation equipment, Sputtering equipment and etc., which uses vacuum technology and mainly forms thin films on a specific substrate.

 $https://www.showashinku.co.jp/product_c/index.html$